

WHAT IS CLAIMED IS:

1. A method of determining terminals of a semiconductor die to contact during test, said method comprising:

selecting a first subset of said terminals not to contact during testing of said die;
covering with an electrically insulative material tip(s) of a first subset of probes corresponding to said first subset of terminals, wherein said first subset of probes composes a plurality of probes corresponding to ones of said terminals;
bringing said plurality of probes into contact with said ones of said terminals of said die; and
verifying testing of said die.

2. The method of claim 1, wherein said first subset of terminals comprises one terminal.

3. The method of claim 1, wherein said first subset of terminals comprises at least two terminals.

4. The method of claim 1, wherein, if said testing of said die does not verify, said method further comprises:

selecting a second subset of said terminals not to contact during testing of said die;
removing said insulative material from said tip(s) of said first subset of probes;
covering with an insulative material tip(s) of a second subset of probes corresponding to said second subset of terminals;
bringing said plurality of probes into contact with said ones of said terminals of said die; and
verifying testing of said die.

5. The method of claim 4, wherein said step of removing said insulative material comprises removing said insulative material by dissolving, laser ablating, peeling, air blasting, water blasting, burning, or subliming said insulative material.

6. The method of claim 1, wherein said plurality of probes are disposed on a probe card.

7. The method of claim 1, wherein said die composes an unsingulated semiconductor wafer.
8. The method of claim 1, wherein said insulative material comprises a material selected from one of an epoxy, a nylon, a starch, a vinyl, a styrene, a polyethylene, a polypropylene, a thermoplastic, or a rubber.
9. The method of claim 1, wherein said plurality of probes are cantilevered beam probes.
10. A probing device comprising:
 - a substrate;
 - a plurality of probes disposed on said substrate, said probes comprising tips disposed to contact terminals of a die to be tested; and
 - insulative material covering one of said tips.
11. The probing device of claim 10, wherein said insulative material covers at least two of said tips.
12. The probing device of claim 10, wherein said insulative material comprises a material selected from one of an epoxy, a nylon, a starch, a vinyl, a styrene, a polyethylene, a polypropylene, a thermoplastic, or a rubber.
13. The probing device of claim 10, wherein said plurality of probes are cantilevered beam probes.
14. The probing device of claim 10, wherein said probing device is a probe card.

15. The probing device of claim 10 further comprising an interface board comprising tester contacts, wherein ones of said tester contacts are electrically connected to ones of said probes.
16. The probing device of claim 15, wherein said interface board comprises a printed circuit board.
17. The probing device of claim 10, wherein said substrate comprises a ceramic.
18. The probing device of claim 10, wherein said substrate comprises a mounting bracket.